# High Voltage PNP Silicon Plastic Power Transistors

These devices are designed for line operated audio output amplifier, switch–mode power supply drivers and other switching applications.

#### Features

- Popular TO–220 Plastic Package
- PNP Complements to the TIP47 thru TIP50 Series
- These Devices are Pb-Free and are RoHS Compliant\*

#### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector–Emitter Voltage MJE5730 MJE5731 MJE5731A	V <sub>CEO</sub>	300 350 375	Vdc
Collector-Base Voltage MJE5730 MJE5731 MJE5731A	V <sub>CB</sub>	300 350 375	Vdc
Emitter–Base Voltage	V <sub>EB</sub>	5.0	Vdc
Collector Current – Continuous	۱ <sub>C</sub>	1.0	Adc
Collector Current – Peak	I <sub>CM</sub>	3.0	Adc
Base Current	I <sub>B</sub>	1.0	Adc
Total Device Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	40 0.32	W W/°C
Total Device Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	2.0 0.016	W W/°C
Unclamped Inducting Load Energy (See Figure 10)	E	20	mJ
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-65 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL CHARACTERISTICS

Characteristics	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	3.125	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\thetaJA}$	62.5	°C/W

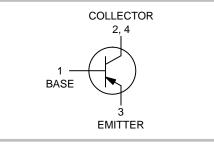
\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

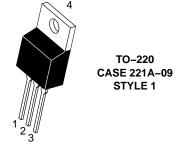


## **ON Semiconductor®**

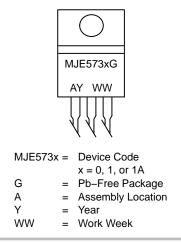
www.onsemi.com

1.0 AMPERE POWER TRANSISTORS PCP SILICON 300–350–400 VOLTS 50 WATTS





### MARKING DIAGRAM



### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

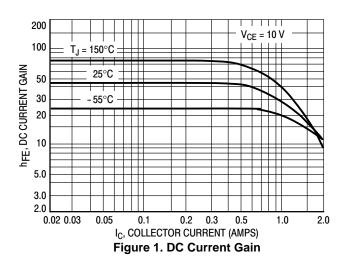
© Semiconductor Components Industries, LLC, 2015 January, 2015 – Rev. 8

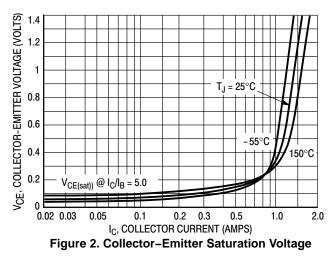
#### **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
	V <sub>CEO(sus)</sub>	300 350 375	_ _ _	Vdc
Collector Cutoff Current $(V_{CE} = 200 \text{ Vdc}, I_B = 0)$ MJE5730 $(V_{CE} = 250 \text{ Vdc}, I_B = 0)$ MJE5731 $(V_{CE} = 200 \text{ Vdc}, I_B = 0)$	ICEO	-	1.0 1.0	mAdc
(V <sub>CE</sub> = 300 Vdc, I <sub>B</sub> = 0) MJE5731A		-	1.0	
Collector Cutoff Current ( $V_{CE} = 300 \text{ Vdc}, V_{BE} = 0$ )	I <sub>CES</sub>			mAdc
MJE5730 (V <sub>CE</sub> = 350 Vdc, V <sub>BE</sub> = 0) MJE5731		-	1.0 1.0	
(V <sub>CE</sub> = 400 Vdc, V <sub>BE</sub> = 0) MJE5731A		-	1.0	
Emitter Cutoff Current ( $V_{BE} = 5.0 \text{ Vdc}, I_C = 0$ )	I <sub>EBO</sub>	_	1.0	mAdc
ON CHARACTERISTICS (Note 1)			•	•
DC Current Gain ( $I_C = 0.3 \text{ Adc}, V_{CE} = 10 \text{ Vdc}$ ) ( $I_C = 1.0 \text{ Adc}, V_{CE} = 10 \text{ Vdc}$ )	h <sub>FE</sub>	30 10	150 -	_
Collector–Emitter Saturation Voltage $(I_C = 1.0 \text{ Adc}, I_B = 0.2 \text{ Adc})$	V <sub>CE(sat)</sub>	_	1.0	Vdc
Base–Emitter On Voltage (I <sub>C</sub> = 1.0 Adc, V <sub>CE</sub> = 10 Vdc)	V <sub>BE(on)</sub>	_	1.5	Vdc
DYNAMIC CHARACTERISTICS			•	•
Current Gain – Bandwidth Product ( $I_C = 0.2 \text{ Adc}, V_{CE} = 10 \text{ Vdc}, f = 2.0 \text{ MHz}$ )	f <sub>T</sub>	10	_	MHz
Small–Signal Current Gain (I <sub>C</sub> = 0.2 Adc, V <sub>CE</sub> = 10 Vdc, f = 1.0 kHz)	h <sub>fe</sub>	25	_	-

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Pulse Test: Pulse Width  $\leq$  300 µs, Duty Cycle  $\leq$  2.0%.





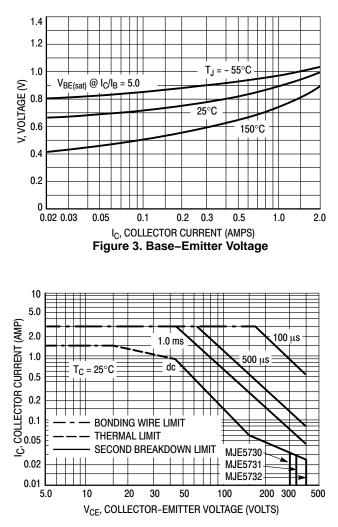
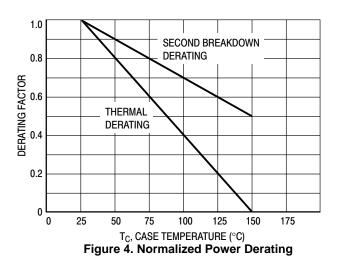


Figure 5. Forward Bias Safe Operating Area



There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate  $I_C - V_{CE}$  limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 5 is based on  $T_{J(pk)} = 150^{\circ}$ C;  $T_{C}$  is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided  $T_{J(pk)} \le 150^{\circ}$ C.  $T_{J(pk)}$  may be calculated from the data in Figure 6. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

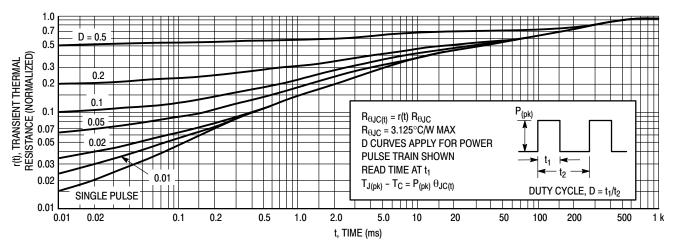
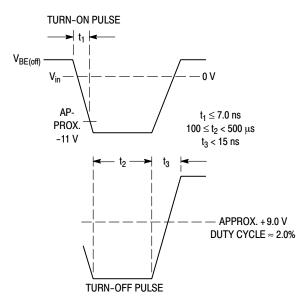


Figure 6. Thermal Response



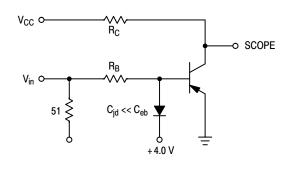


Figure 7. Switching Time Equivalent Circuit

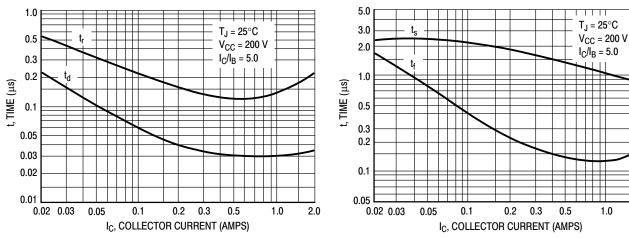
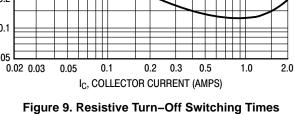
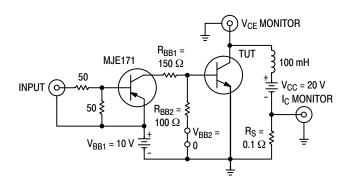


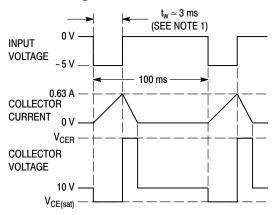
Figure 8. Turn-On Resistive Switching Times





#### **Test Circuit**







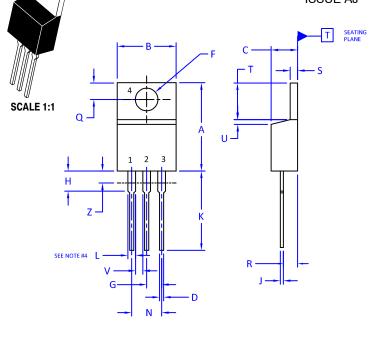
#### **ORDERING INFORMATION**

Device	Package	Shipping
MJE5730G	TO–220 (Pb–Free)	50 Units / Rail
MJE5731G	TO–220 (Pb–Free)	50 Units / Rail
MJE5731AG	TO-220 (Pb-Free)	50 Units / Rail

DATE 05 NOV 2019



TO-220 CASE 221A-09 ISSUE AJ



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 2009.

2. CONTROLLING DIMENSION: INCHES

3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

4. MAX WIDTH FOR F102 DEVICE = 1.35MM

	INCHES		MILLIMETERS	
DIM	MIN.	MAX.	MIN.	MAX.
А	0.570	0.620	14.48	15.75
В	0.380	0.415	9.66	10.53
С	0.160	0.190	4.07	4.83
D	0.025	0.038	0.64	0.96
F	0.142	0.161	3.60	4.09
G	0.095	0.105	2.42	2.66
Н	0.110	0.161	2.80	4.10
J	0.014	0.024	0.36	0.61
К	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
Ν	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.41
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045		1.15	
Z		0.080		2.04

STYLE 1: PIN 1. 2. 3. 4.	COLLECTOR EMITTER	STYLE 2: PIN 1. 2. 3. 4.	EMITTER COLLECTOR	2. 3.	CATHODE ANODE GATE ANODE	STYLE 4: PIN 1. 2. 3. 4.	MAIN TERMINAL 1 MAIN TERMINAL 2 GATE MAIN TERMINAL 2
STYLE 5: PIN 1. 2. 3. 4.	DRAIN SOURCE	2. 3.	ANODE CATHODE ANODE CATHODE	2. 3.	CATHODE ANODE CATHODE ANODE	2. 3.	CATHODE ANODE EXTERNAL TRIP/DELAY ANODE
STYLE 9: PIN 1. 2. 3. 4.	COLLECTOR EMITTER	STYLE 10: PIN 1. 2. 3. 4.	GATE SOURCE DRAIN		DRAIN SOURCE GATE	STYLE 12 PIN 1. 2. 3. 4.	MAIN TERMINAL 1 MAIN TERMINAL 2 GATE NOT CONNECTED

DOCUMENT NUMBER:	98ASB42148B	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	DN: TO-220 PAGE 1 OF		PAGE 1 OF 1	
ON Semiconductor and  are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.				

 $\ensuremath{\textcircled{}}$  Semiconductor Components Industries, LLC, 2019

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <u>www.onsemi.com/site/pdf/Patent-Marking.pdf</u>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor and the support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconducts harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized claim alleges that

#### PUBLICATION ORDERING INFORMATION

#### LITERATURE FULFILLMENT: Email Requests to: orderlit@onsemi.com

#### TECHNICAL SUPPORT

ON Semiconductor Website: www.onsemi.com

#### North American Technical Support: Voice Mail: 1 800–282–9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support: Phone: 00421 33 790 2910 For additional information, please contact your local Sales Representative

٥